



Your Trusted Partner in Semiconductor Testing

TWSE

6515

Investor Presentation

2025.11.20

Safe Harbor Notice



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WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

Founded

2001.4.10

Chairman & CEO

Mark Wang

Business Operation

Design, manufacture, sale and service of test interface products

Employees

1068

Capital Stock

NTD 360,491,820

Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist.
Kaohsiung City, Taiwan



USA Branch Office



Kaohsiung Headquarter



Hsinchu Branch Office

Company Vision



Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.



Quality

We exceed customers' quality requirements by offering cost-effective total solutions and on-time delivery worldwide.



Service

We strive to become the world's leading professional testing service provider in all phases of IC testing.

Agenda



01

**Global
Presence**

02

**Industry
Trend**

03

**Financial
Performance**

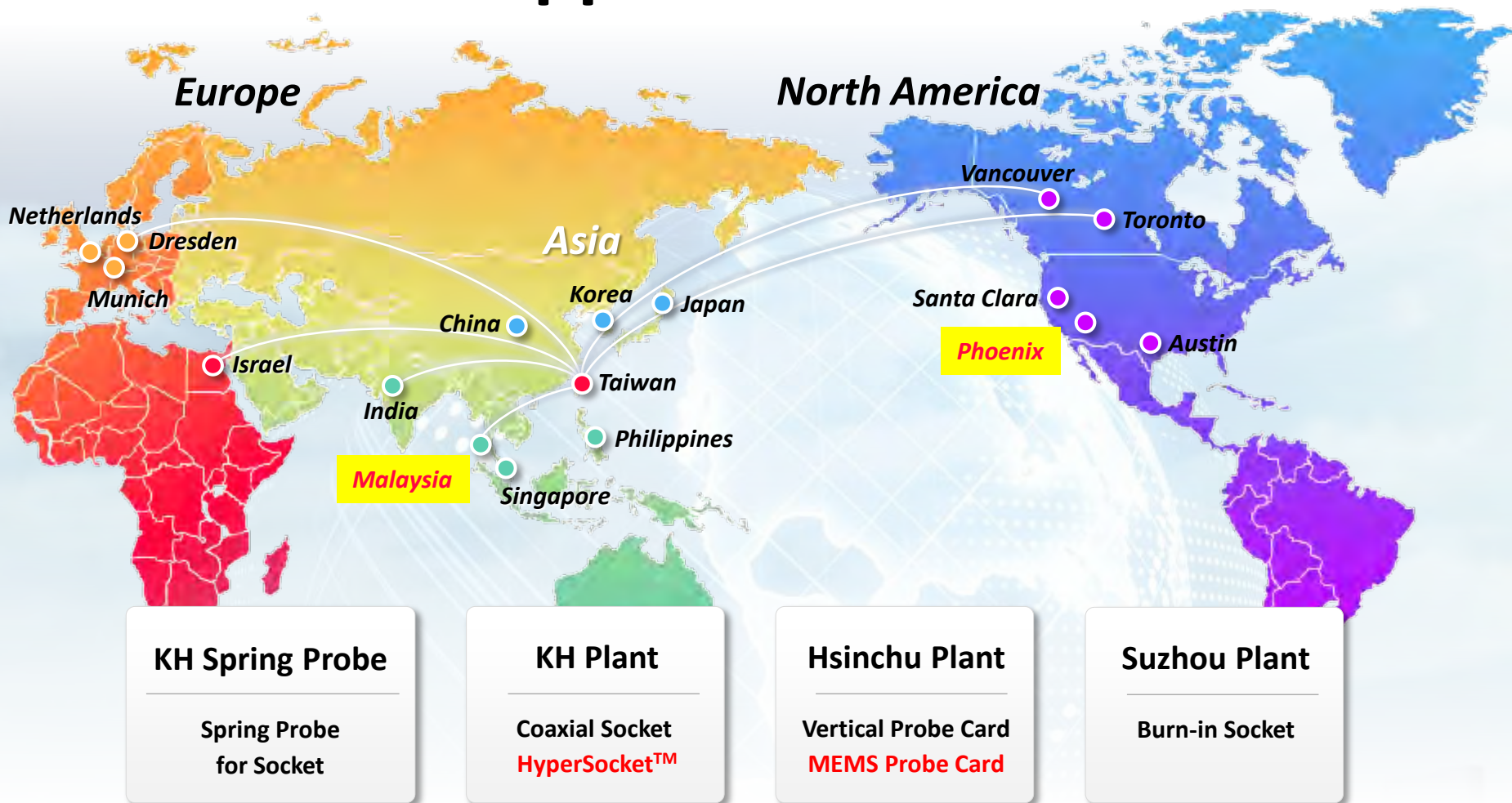
04

**R&D
Innovation**



01 Global Presence

Global Service & Support Network



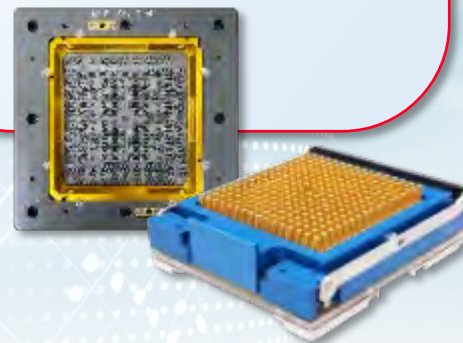
Semiconductor Test Interface Leadership

2024
Test Socket Ranking

NO. 1

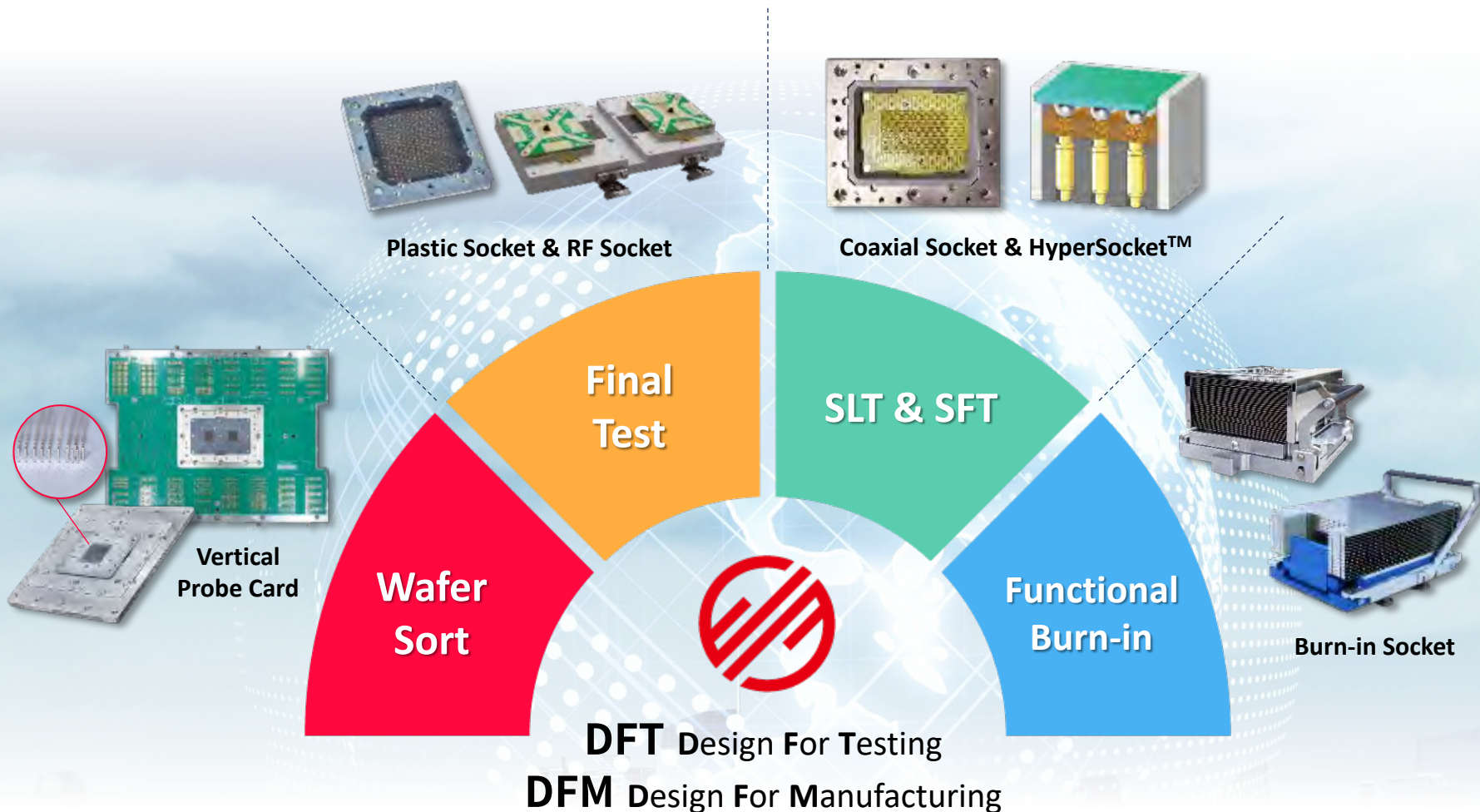
2024
**Test and Burn-in Socket
Ranking**

NO. 2



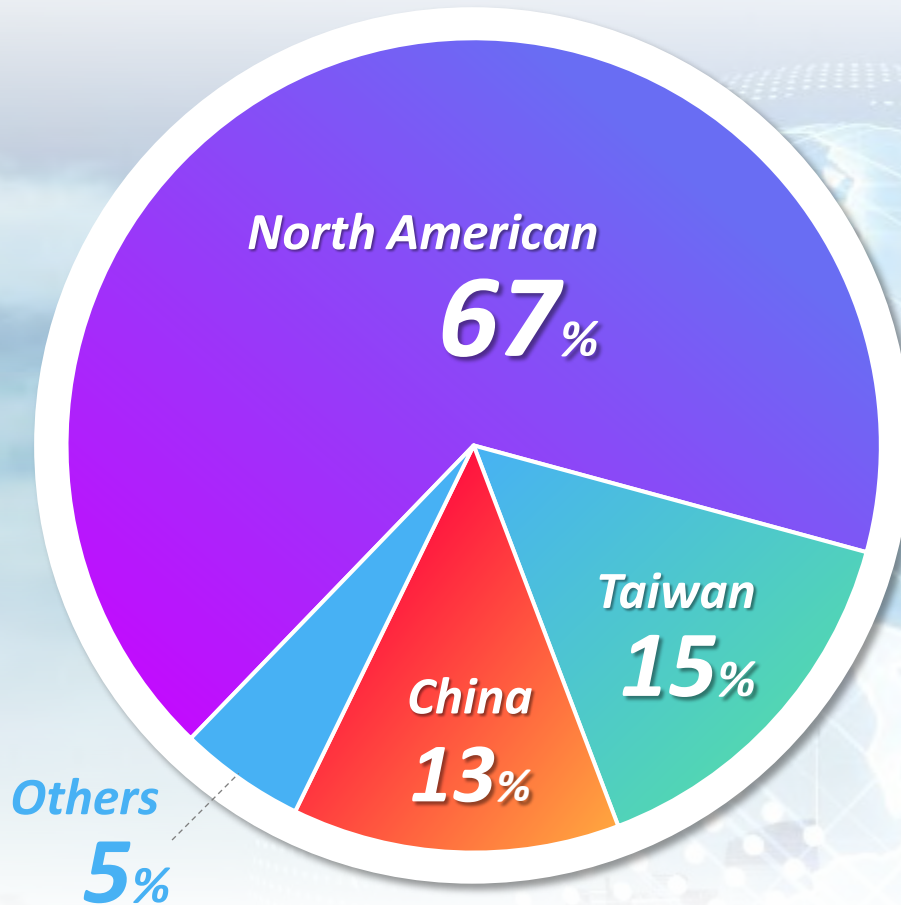
Source : Yole Intelligence, 2025/04

Your Trusted Partner in Semiconductor Testing



Worldwide Customer

First 10 Months of 2025



87% Top10 Customers

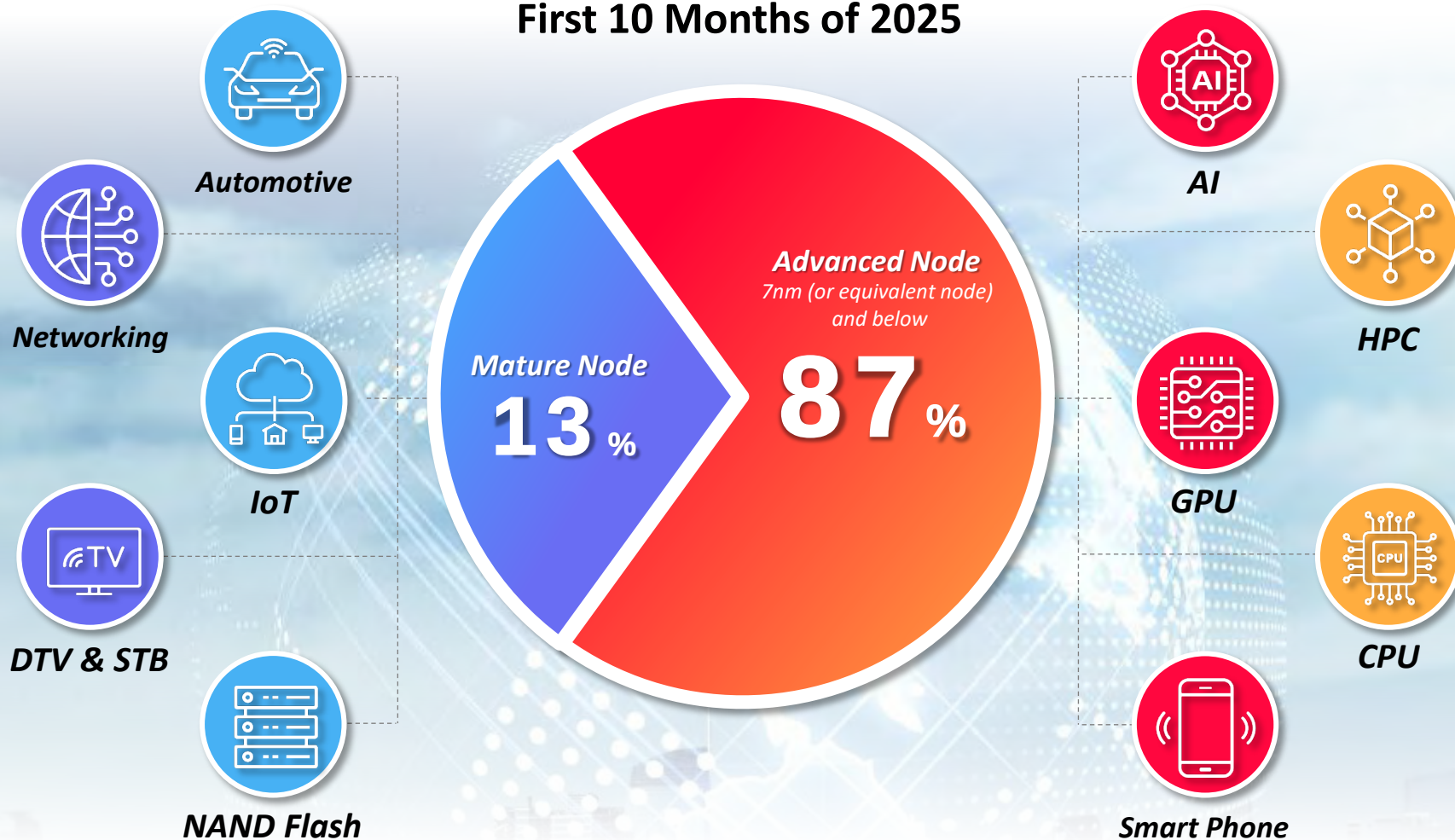
■ AI ■ ASIC ■ CPU
■ HPC ■ AP ■ GPU

200+ Active Customers

■ IC Design ■ Foundry ■ OSAT
■ CSP ■ ASIC ■ IDM

Bolstered by Advanced Technology

First 10 Months of 2025



High Performance Testing Driven by Advanced Packaging

Large
Package

CoWoS

High Power

High
Frequency

Chiplet

CPO

High Speed

HyperSocket™



02 Industry Trend

Driving Force for AI



Greater Importance on Chip Probing

From the Shadows to the Spotlight

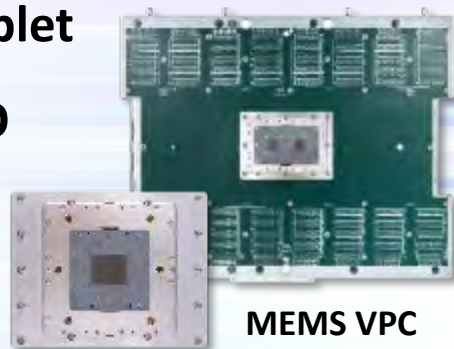
K.G.D

Close to
Known **G**ood **D**ie

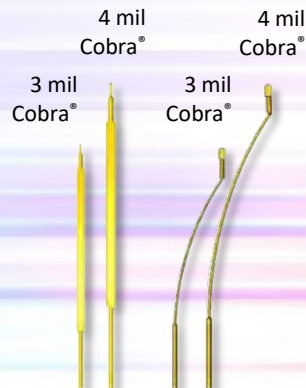
■ CoWoS

■ Chiplet

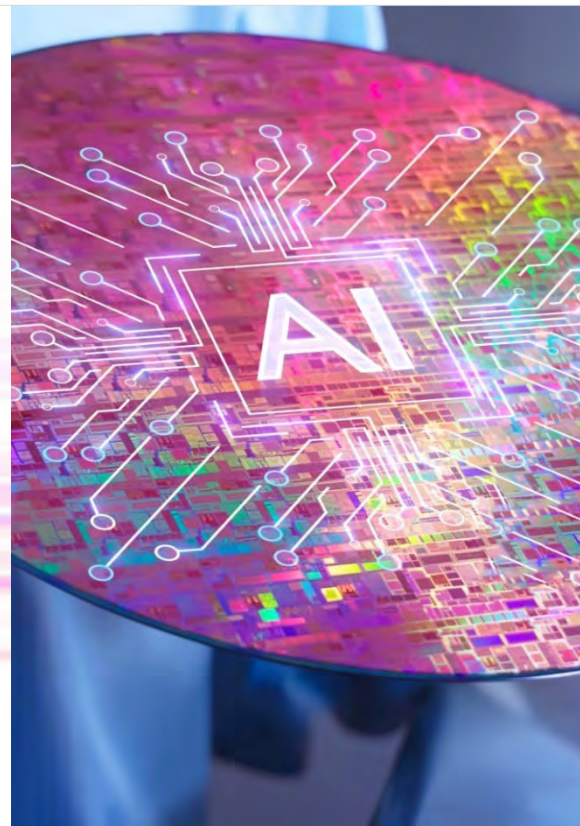
■ CPO



MEMS VPC



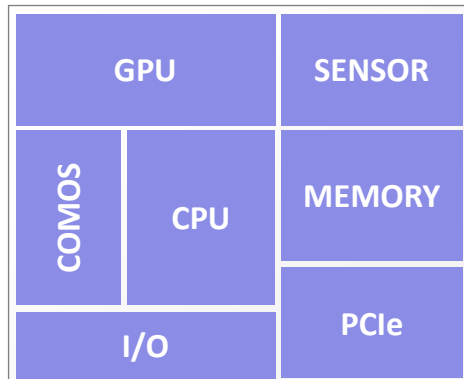
Cobra VPC



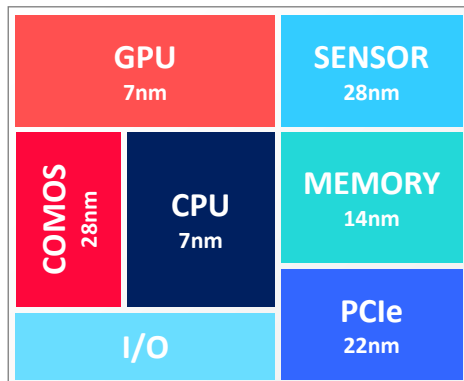
Known Good Die Is Required!

Probe Card Demand Induce

SoC One Probe Card

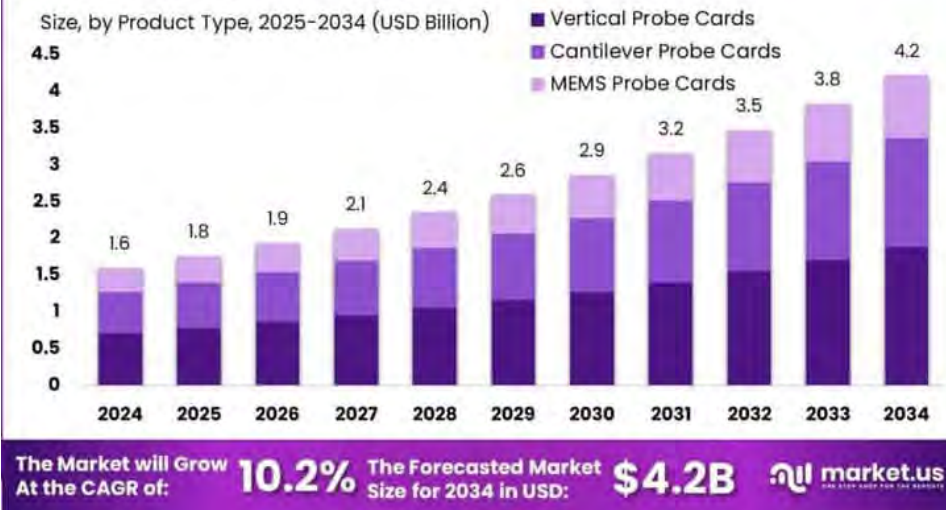


Chiplet Multiple Probe Card Demand



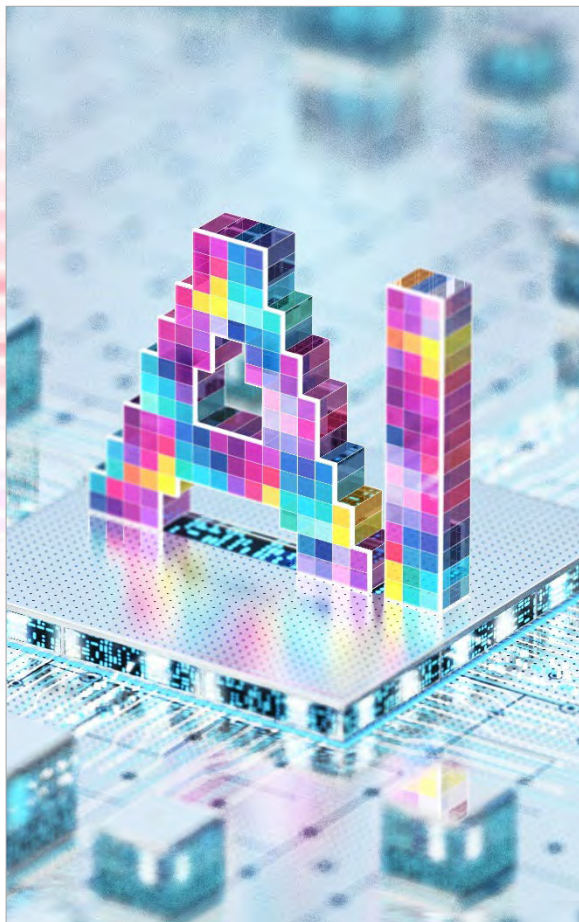
Source : Trend Force

Global Mems High Density Probe Cards Market



- Higher Pin Count
- Higher CCC
- Higher Speed
- Lower Force
- Smaller Pitch
- Wider Operation Temperature

Accelerated SLT Demand Driven by AI



2026-2030 CAGR

SLT & SFT

More than
Greater than
industry growth

15%

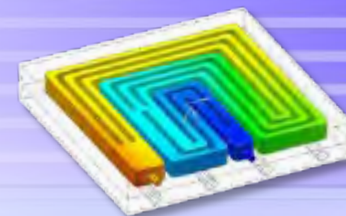
Source: WinWay 2025



HyperSocket™

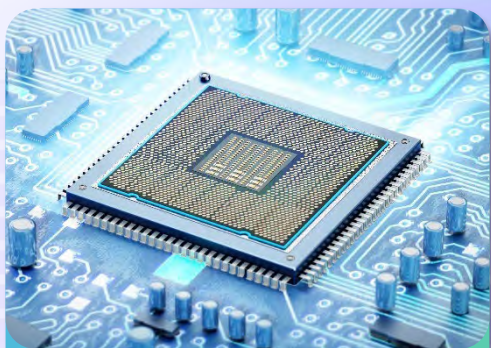


Coaxial Socket



**(Liquid Cooling)
Thermal System**

Emerging Trend Toward Functional Burn-In



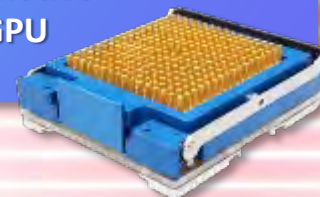
Reliability Burn-in
For all IC testing



Functional Burn-in
AI & HPC



Mass Production
Burn-in
Automotive
CPU GPU



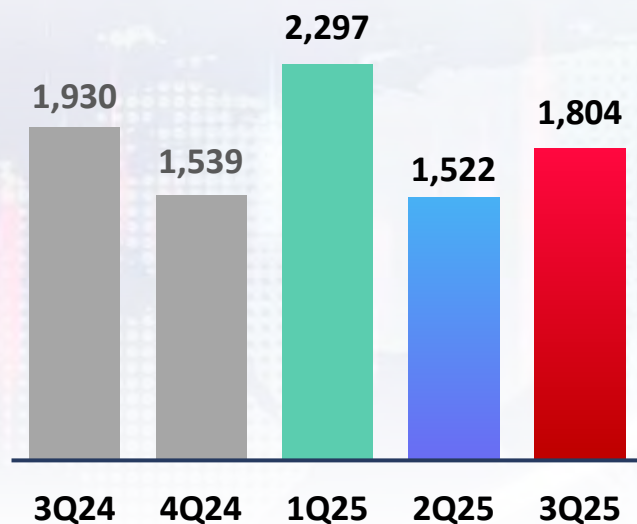


03 Financial Performance

Revenue Trend

QUARTERLY REVENUE

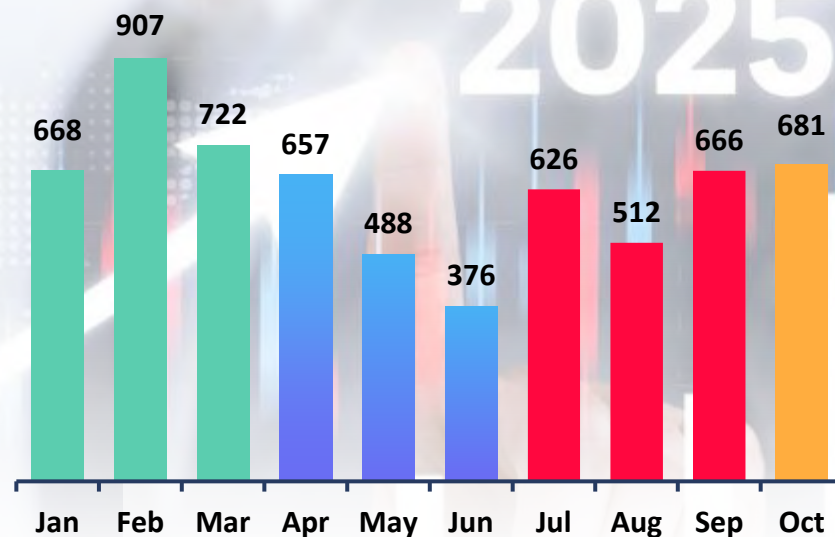
(NTD MILLION)



YoY	96%	129%	114%	21%	-7%
QoQ	54%	-20%	49%	-34%	19%

MONTHLY REVENUE

(NTD MILLION)



YoY	82%	191%	84%	40%	37%	-12%	5%	-18%	-6%	5%
MoM	47%	36%	-20%	-9%	-26%	-23%	66%	-18%	30%	2%

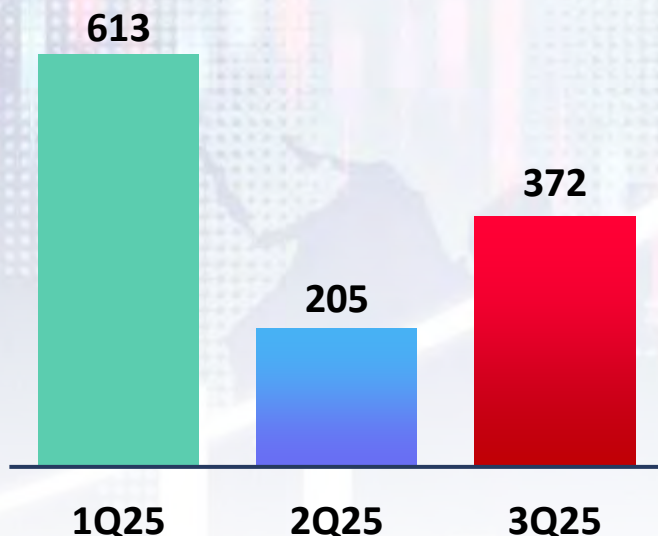
Profitability Trend

2025
Q1-Q3 EPS **33.4** (NT\$)

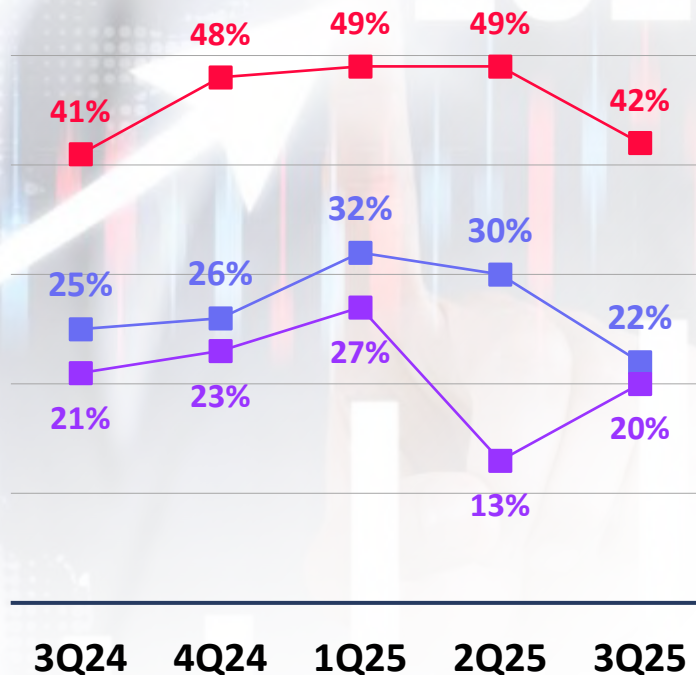
EPS

17.21	5.76	10.43
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NET INCOME (NTD M)



— Gross Margin — Operating Margin — Net Margin



Revenue by Product Mix

First 10 Months of 2025

 Coaxial Socket **41 %**

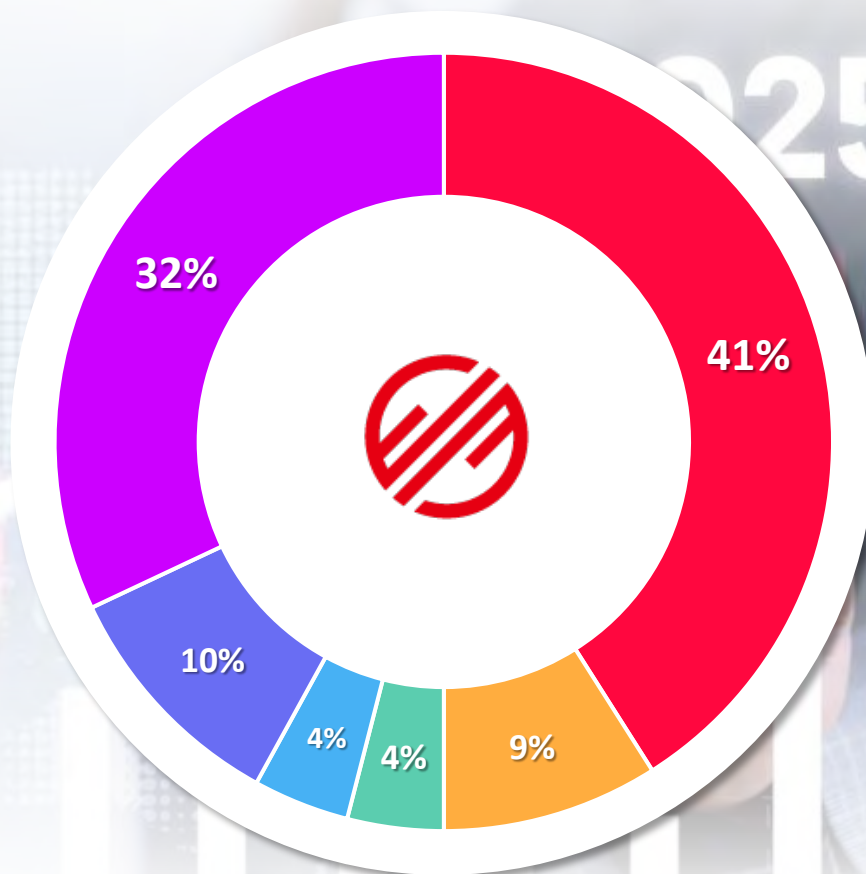
 Probe Card **32 %**

 Contact Element **10 %**

 RF & Plastic Socket **9 %**

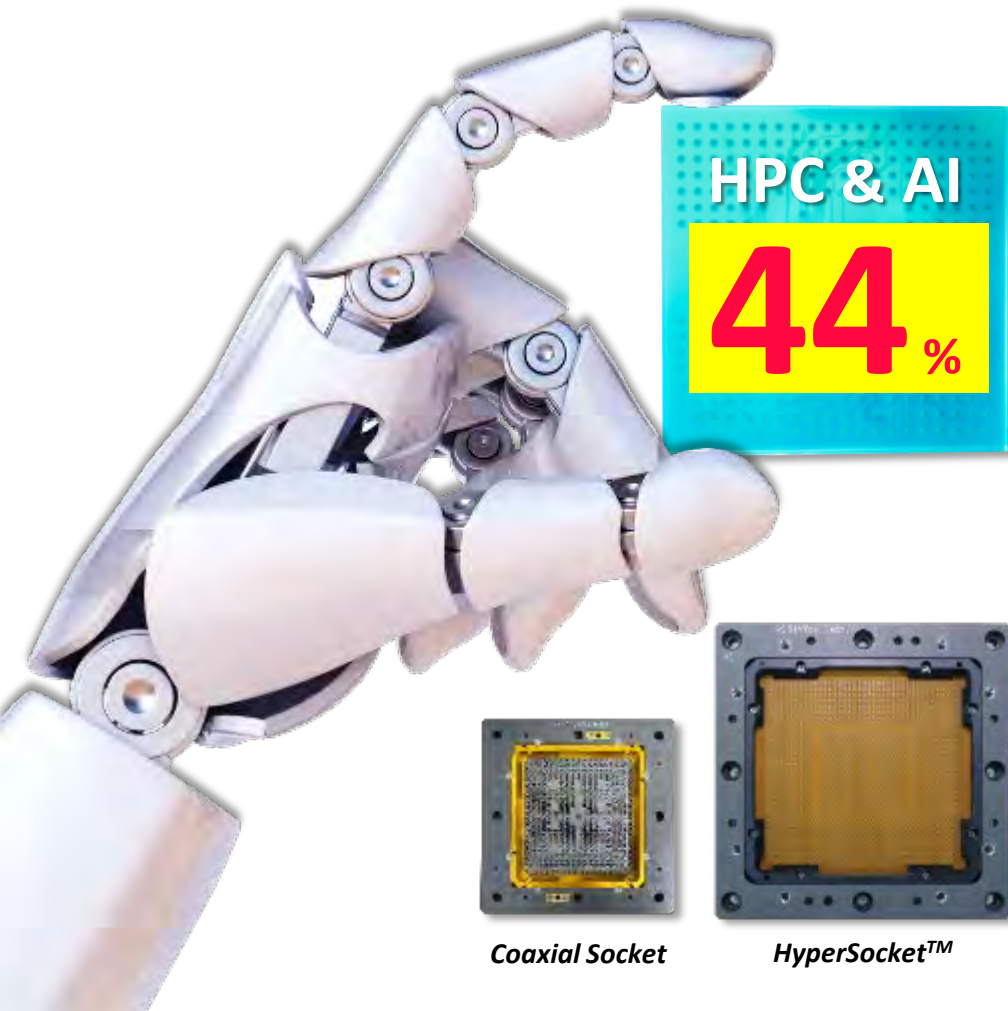
 Burn-in Socket **4 %**

 Others **4 %**



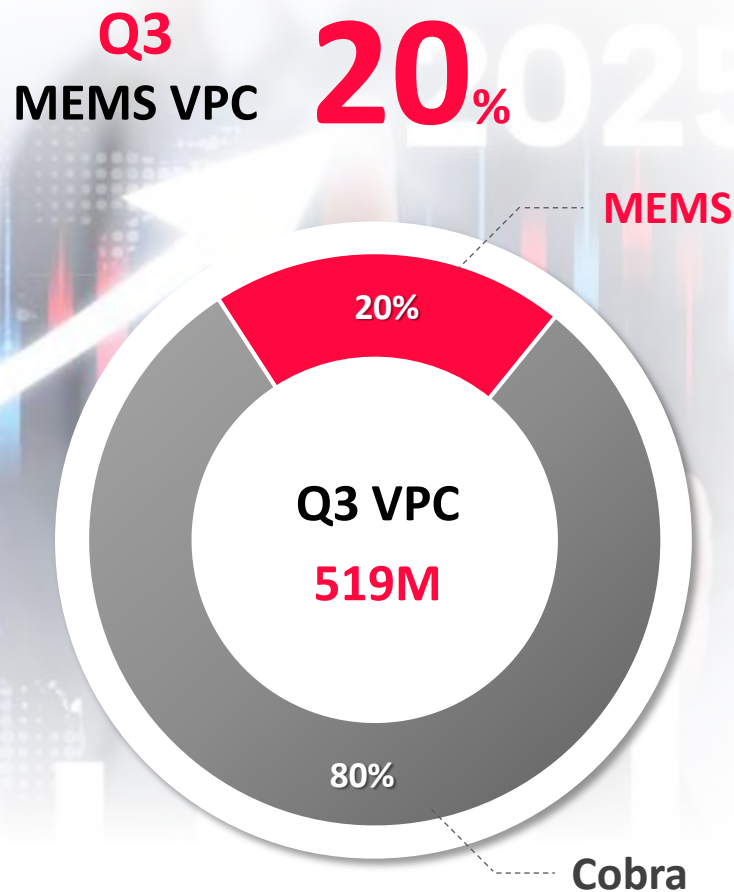
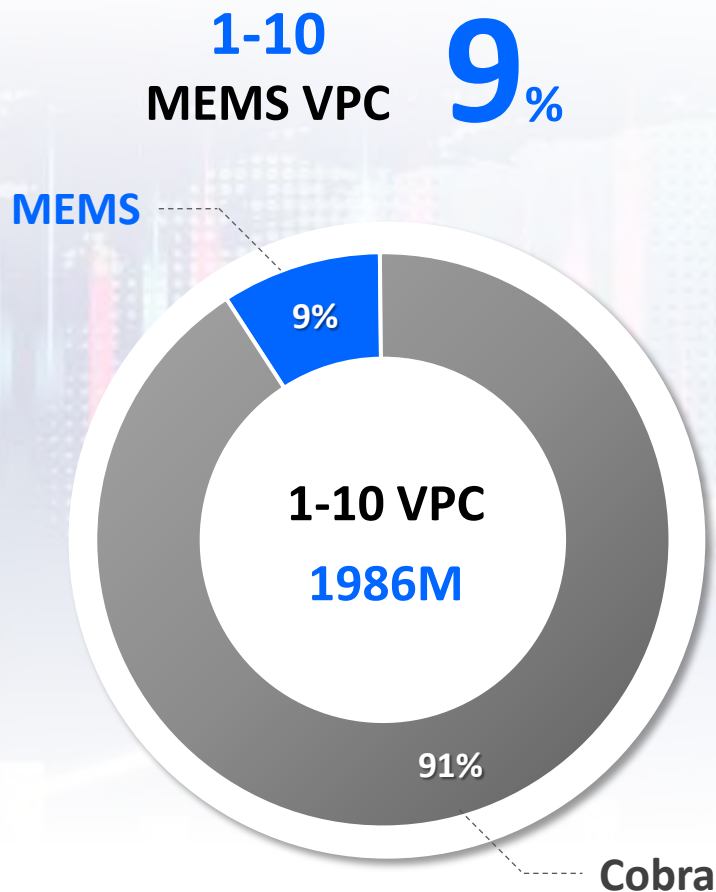
Revenue by End Market

First 10 Months of 2025



MEMS Probe Card

First 10 Months of 2025





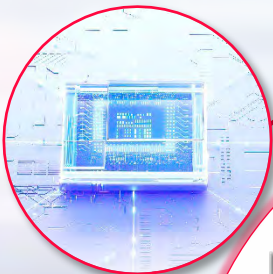
04 R&D Innovation

Innovative Semiconductor Test Interface Solution

HyperSocket™-Dual Film

Large Package

Larger contact area
Improved heat dissipation
Enhanced test stability



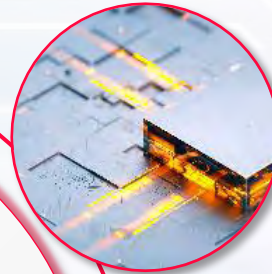
High Power

Various current pathways
Mitigating temperature rise



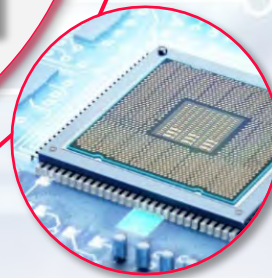
High Speed

Full metal shielding,
short-loop design
Test speed above 224Gbps



High Pin Counts

Zero Pre-load design
Reduced maintenance cost



Patent NO.

TWI862047

TWI884802

TWI862191

TWI901161

CN20570508U

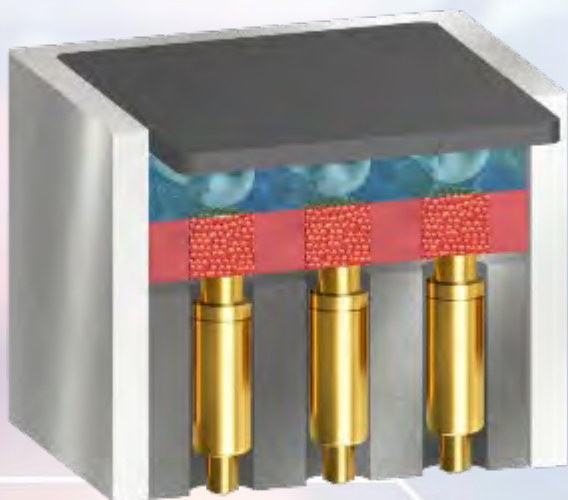
Patent Pending

USA

Malaysia

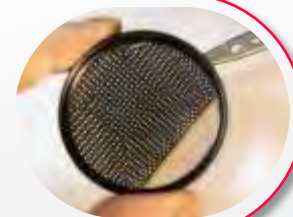
Innovative Semiconductor Test Interface Solution

Liquid Cooling Socket



Patent NO. TWI901181

Extraordinary heat
dissipation



Improved Test Stability
for Advanced Packaging

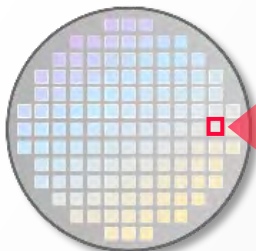


Extend Spring
Probe Lifespan



Co-Packaged Optics Test Solution

Wafer Level → Die Level



Silicon Photonic Wafer



EIC/PIC Die

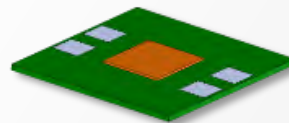


WLCSP Fine Pitch Socket
(PIC & EIC Wafer test)

Package Level



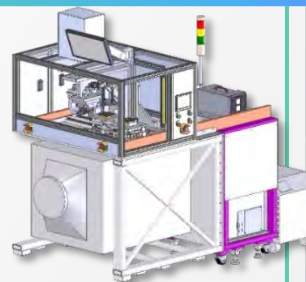
Optical Engine



CPO Substrate

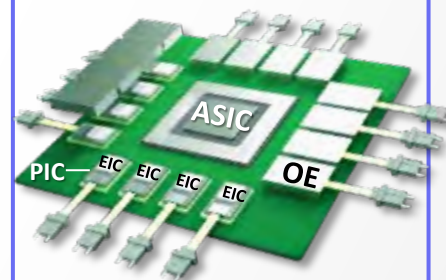


Optical and Electrical Test Socket
(Optical Engine)



Double Sided Probing System

Module Level



CPO Module
Source: ASE Holdings



Coaxial Socket

High Power Thermal Solution

E-Flux6.0 3500W Liquid Cooling System



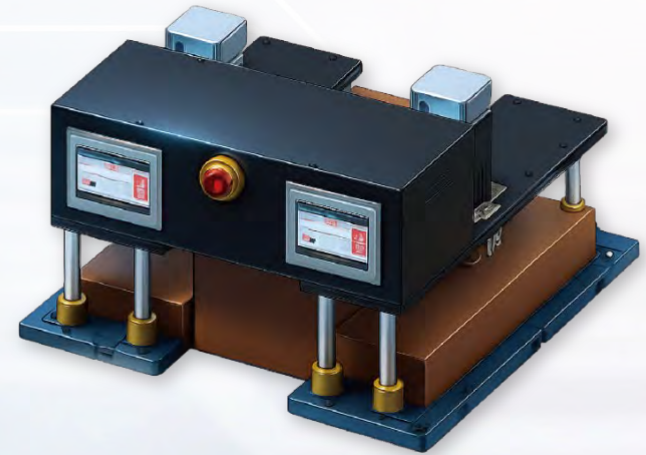
AI Server Board-Level Test



AI Data Center



AI Server



SLT Plunger System

Spring Probe Manufacturing

Socket All in House



Cost Optimization

Balanced insourcing, better cost structure

Self-Sufficiency

Autonomy of critical process technology

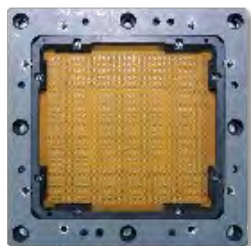
Quality Assurance

Greater customer experience

Operational Resilience

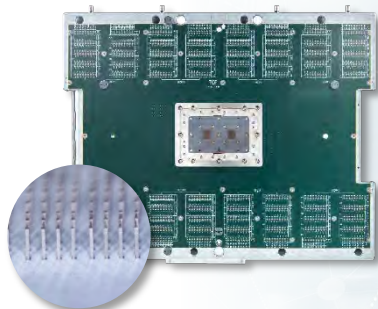
More flexible, agile lead time

Pillars of Business Growth



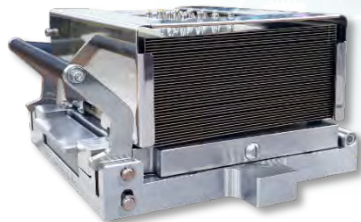
HyperSocket™

Positioned for advanced packaging



MEMS Probe Card

Localized service for AI/HPC

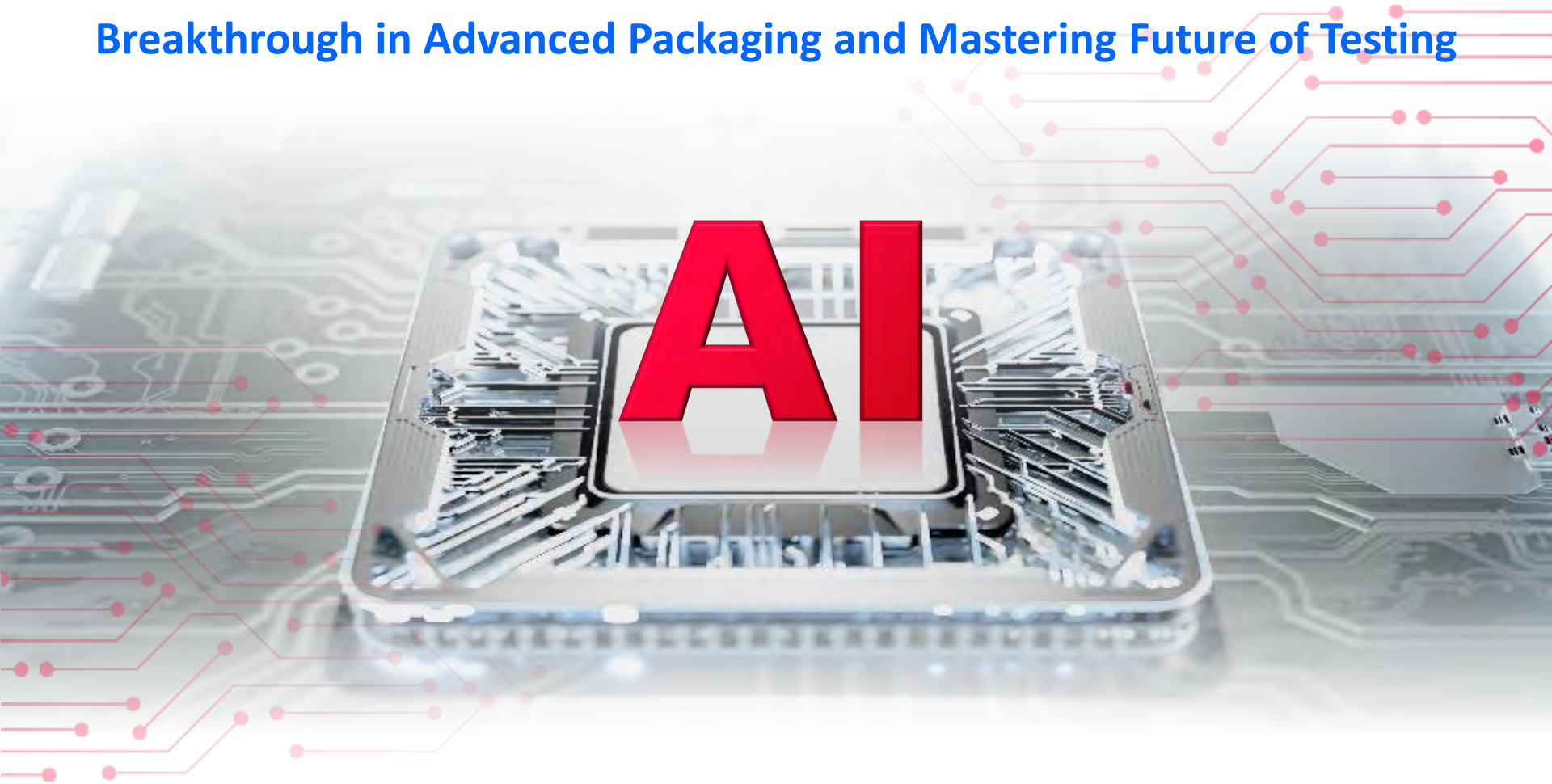


Functional Burn-in

Pioneer in emerging application

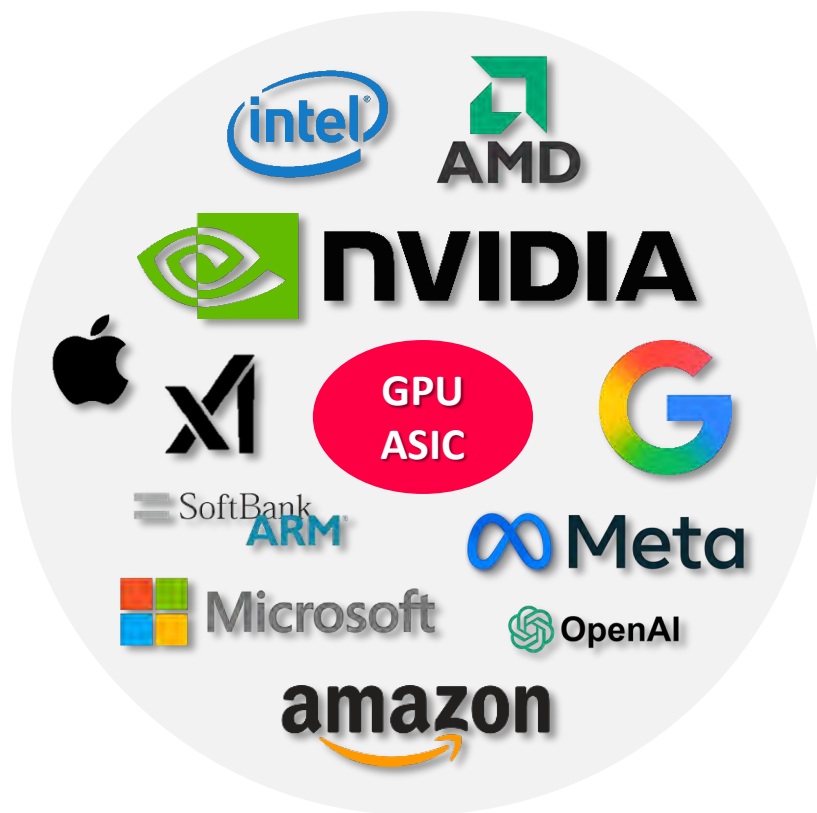
Challenges and Opportunities:

Breakthrough in Advanced Packaging and Mastering Future of Testing

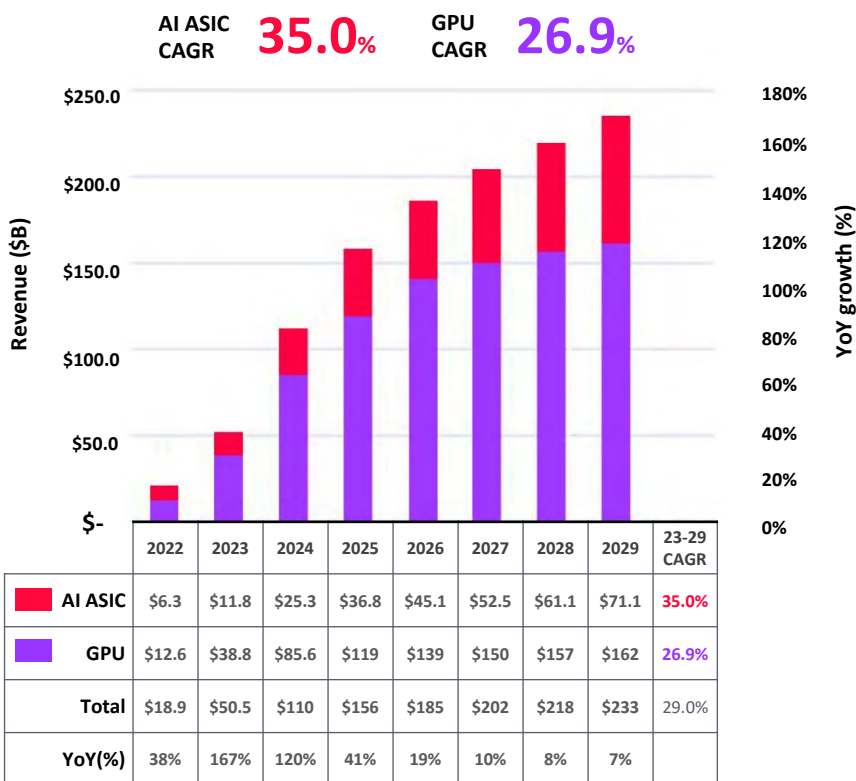


Advanced Package Application and Market Trend

Data Center AI Chip & ASIC



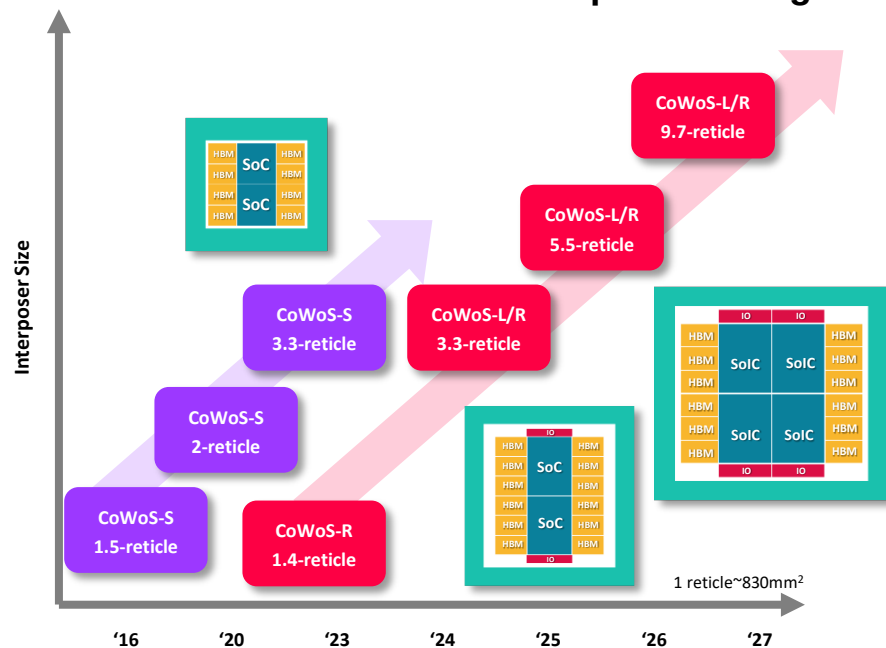
Datacenter GPU and AI ASIC revenue forecast



Source: Yole

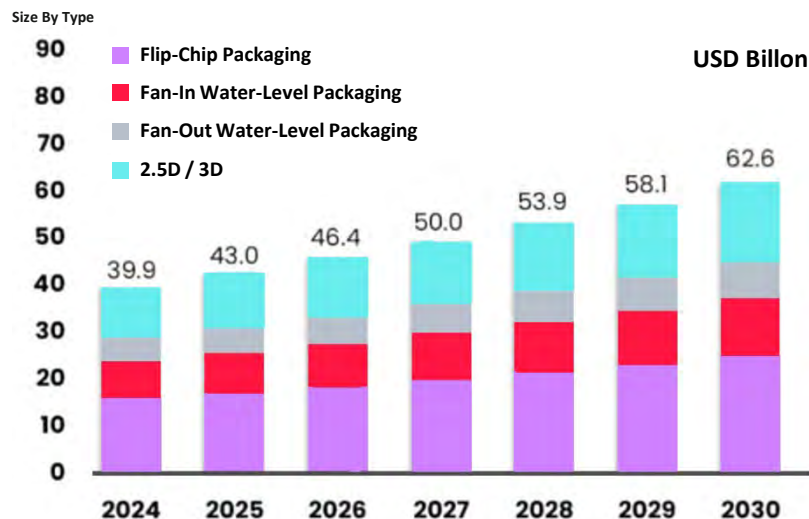
Advanced Package Application and Market Trend

CoWoS Enables AI Compute Scaling



Source: TSMC

Global Advanced Semiconductor Packaging Market



The Forecasted Market Size for 2030 is USD

\$62.6B

The Market will Grow At the CAGR of

7.8%

Source: market.us

Significant Increase in Testing Time

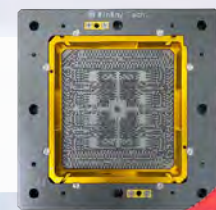
Longer Wafer Sort Test Time

MEMS and Cobra Probe card



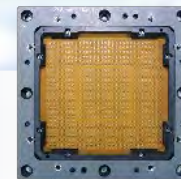
Longer FT (ATE) Test Time

Plastic, Coaxial and HyperSocket™



Longer SLT Test Time

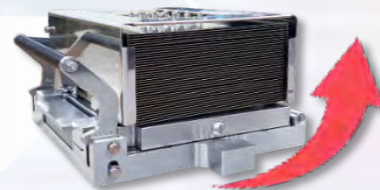
Coaxial and HyperSocket™



More Test Insertions

More Reliability Test Insertion

Functional Burn-In Socket



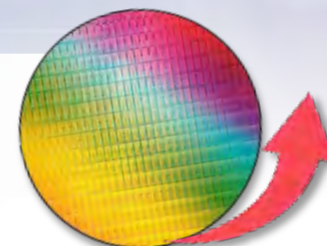
**Bigger and Bigger Device Package
Higher and Higher Device Power Consumption**

HyperSocket™ and HyperSocket™-DF



Longer and Longer Fab In-process Time

Fab and OSAT expansion drive equipment demand

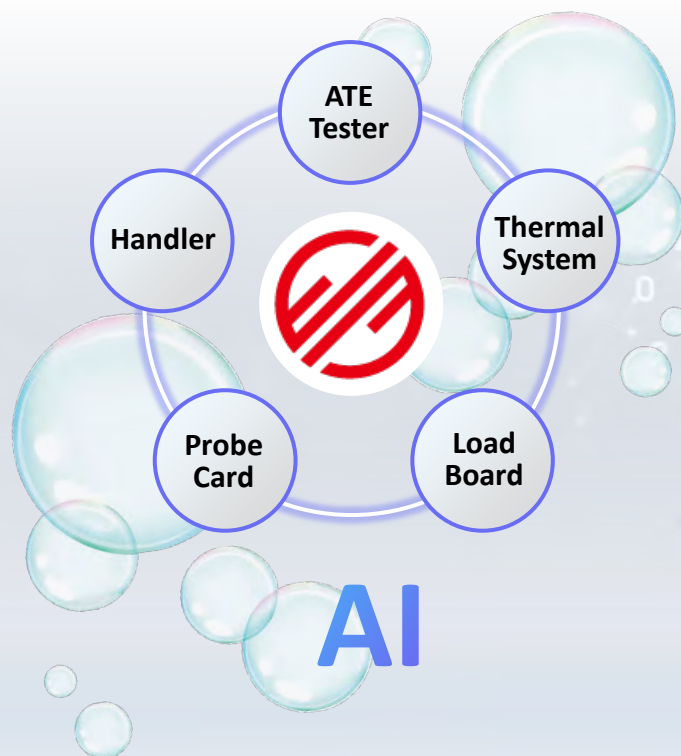


Industry Alliance and Integration Across Heterogeneous Disciplines

Alliance

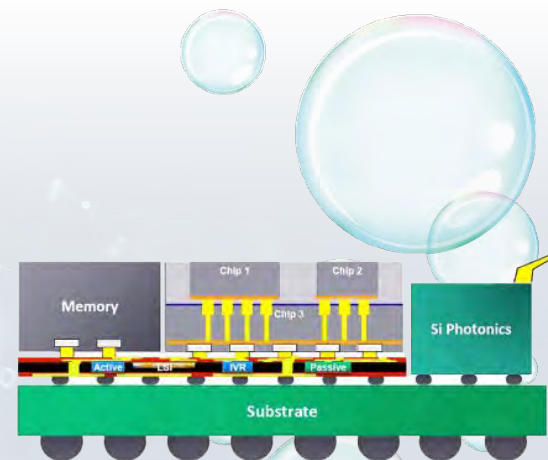
Integration

Heterogeneous



Artificial Intelligence

CPU、GPU、HPC



Source: TSMC

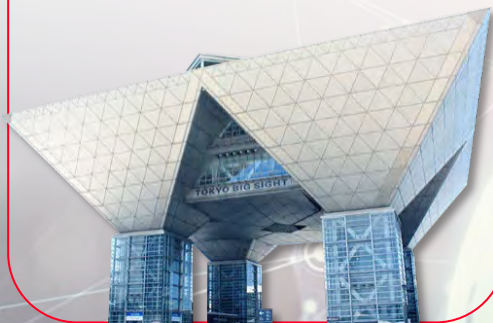
SEMICON JAPAN

2025.12.17—19



Japan

Tokyo Big Sight, Tokyo



SEMICON China

2026.03.25—27



China

**Shanghai New
International Expo Centre**



SEMICON SEA

2026.05.05—07



Malaysia

**Malaysia International
Trade & Exhibition Centre**



Q & A

■ ■ ■ ■ ■ TWSE 6515

THANK YOU

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